

## PATENT ASSIGNMENT

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Jayavel Pachamuthu</td> <td>02/19/2013</td> </tr> <tr> <td>Hiroyuki Kinoshita</td> <td>02/19/2013</td> </tr> <tr> <td>Vinod R. Purayath</td> <td>02/25/2013</td> </tr> <tr> <td>George Matamis</td> <td>02/19/2013</td> </tr> </tbody> </table>		Name	Execution Date	Jayavel Pachamuthu	02/19/2013	Hiroyuki Kinoshita	02/19/2013	Vinod R. Purayath	02/25/2013	George Matamis	02/19/2013
Name	Execution Date										
Jayavel Pachamuthu	02/19/2013										
Hiroyuki Kinoshita	02/19/2013										
Vinod R. Purayath	02/25/2013										
George Matamis	02/19/2013										
RECEIVING PARTY DATA											
Name:	SanDisk Technologies Inc.										
Street Address:	Two Legacy Town Center										
Internal Address:	6900 North Dallas Parkway										
City:	Plano										
State/Country:	TEXAS										
Postal Code:	75024										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13768934</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13768934						
Property Type	Number										
Application Number:	13768934										
CORRESPONDENCE DATA											
Fax Number:	4154894150										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
Phone:	415-489-4100										
Email:	wgoy@vierramagen.com										
Correspondent Name:	David E. Cromer										
Address Line 1:	Vierra Magen Marcus										
Address Line 2:	575 Market St., Suite 3750										
Address Line 4:	San Francisco, CALIFORNIA 94105										
ATTORNEY DOCKET NUMBER:	SAND-01566US1 (SDUF)										
NAME OF SUBMITTER:	David E. Cromer										

CH \$40.00 13768934

**Total Attachments: 5**

source=1566us1-assignment-signed#page1.tif

source=1566us1-assignment-signed#page2.tif

source=1566us1-assignment-signed#page3.tif

source=1566us1-assignment-signed#page4.tif

source=1566us1-assignment-signed#page5.tif

**JOINT TO CORPORATE ASSIGNMENT**

WHEREAS, the undersigned Inventors:

- (1) Jayavel Pachamuthu, a resident of Milpitas, California;
- (2) Hiroyuki Kinoshita, a resident of San Jose, California;
- (3) Vinod R. Purayath, a resident of Santa Clara, California, and
- (4) George Matamis, a resident of Milpitas, California; and

have invented certain new and useful improvements in:

METAL LAYER AIR GAP FORMATION

and have executed a declaration for an application for a United States Patent disclosing and identifying the invention, said application having Application Number 13/768,934 and filed on the 15<sup>th</sup> day of February 2013.

WHEREAS SanDisk Technologies Inc. (hereinafter termed "Assignee"), a corporation of the State of Texas, having a place of business at Two Legacy Town Center, 6900 North Dallas Parkway, Plano, State of Texas, wishes to acquire the entire right, title and interest in and to said application and the invention disclosed therein, and in and to all embodiments of the invention, heretofore conceived, made or discovered jointly or severally by said Inventors (all collectively hereinafter termed "said invention"), and in and to any and all patents, certificates of invention and other forms of protection thereon (hereinafter termed "patents") applied for or granted in the United States and/or other countries.

NOW THEREFORE, for good and valuable consideration acknowledged by each of said Inventors to have been received in full from said Assignee:

1. Said Inventors do hereby sell, assign, transfer and convey to said Assignee, the entire right, title and interest (a) in and to said application and said invention; (b) in and to all rights to apply in any or all countries of the world for patents, certificates of inventions or other governmental grants on said invention, including the right to apply for patents pursuant to the International Convention for the Protection of Industrial Property or pursuant to any other convention, treaty, agreement or understanding; (c) in and to any and all applications filed and any and all patents, certificates of inventions or other governmental grants granted on said invention in the United States or any other country, including each and every application filed and each and every patent granted on any application which is a division, substitution, or continuation of any of said applications; (d) in and to each and every reissue or extension of any of said patents; and (e) in and to each and every patent claim resulting from a reexamination certificate for any and all of said patents.

2. Said Inventors hereby jointly and severally covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest herein conveyed in the United States and other countries. Such cooperation by said Inventors shall include prompt production of pertinent facts and documents, giving of testimony, executing of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for complying with any duty of disclosure; (c) for prosecuting any of said applications; (d) for filing and prosecuting substitute, divisional, continuing or additional applications covering said invention; (e) for filing and prosecuting applications for reissue of any of said patents; (f) for interference or other priority proceedings involving said invention; and (g) for legal proceedings involving said invention and any applications therefor and any patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, reexamination proceedings, compulsory licensing proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Inventors in providing such cooperation shall be paid for by said Assignee.

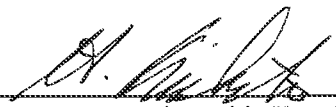
3. The terms and covenants of this Assignment shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Inventors, their respective heirs, legal representatives and assigns.

4. Said Inventors hereby jointly and severally warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

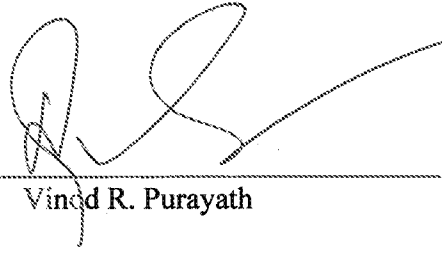
Date: 02/19/13

(1)   
\* Jayavel Pachamuthu

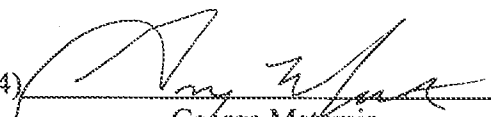
Date: 2/19/13

(2)   
Hiroyuki Kinoshita

Date: 02/25/2013

(3)   
\_\_\_\_\_  
Vinod R. Purayath

Date: 2/19/13

(4)   
George Matamis